DGG OR DL PACKAGE

SCES047 - AUGUST 1995

- Member of the Texas Instruments
 Widebus™ Family
- EPIC ™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 2 V at V_{CC} = 3.3 V, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- All Outputs Have Equivalent 26-Ω Series Resistors, So No External Resistors Are Required
- Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

description

This 16-bit (dual-octal) noninverting bus transceiver is designed for 2.7-V to 3.6-V V_{CC} operation

The SN74LVCR162245 is designed for asynchronous communication between data buses. The control function implementation minimizes external timing requirements.

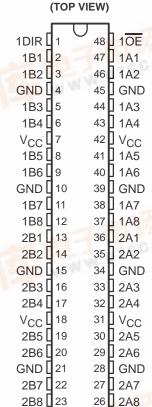
This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so that the buses are effectively isolated.

All outputs, which are designed to sink up to 12 mA, include $26-\Omega$ resistors to reduce overshoot and undershoot.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVCR162245 is characterized for operation from -40°C to 85°C.



2DIR 24

25 20E

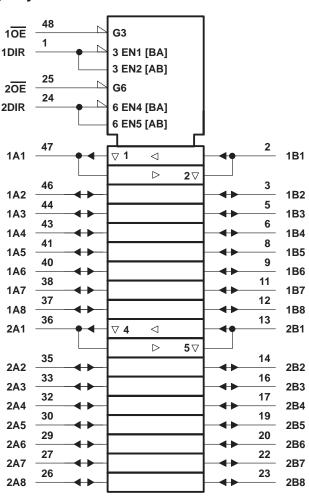
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TEXAS

FUNCTION TABLE (each 8-bit section)

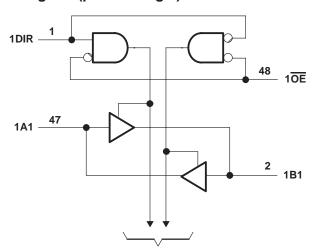
INPUTS		OPERATION				
OE	DIR	OPERATION				
L	L	B data to A bus				
L	Н	A data to B bus				
Н	X	Isolation				

logic symbol†

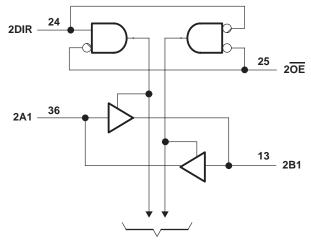


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Seven Other Channels



To Seven Other Channels



SCES047 - AUGUST 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 4.6 V
Input voltage range, VI: Except I/O ports (see Note 1)	-0.5 V to V _{CC} + 4.6 V
I/O ports (see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, VO (see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 3): DGG package	0.85 W
DL package	1.2 W
Storage temperature range, T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Vcc	Supply voltage		2.7	3.6	V	
VIH	High-level input voltage	V _{CC} = 2.7 V to 3.6 V	2		V	
VIL	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	V	
٧ _I	Input voltage		0	VCC	V	
Vo	Output voltage	utput voltage			V	
	High-level output current	V _{CC} = 2.7 V		-8	mA	
ЮН		V _{CC} = 3 V		-12	IIIA	
lOL	Low-level output current			8	A	
	Low-level output current	V _{CC} = 3 V		12	mA	
Δt/ΔV	Input transition rise or fall rate		0	10	ns/V	
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.



SN74LVCR162245 **16-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS**

SCES047 - AUGUST 1995

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAI	RAMETER	TEST C	ONDITIONS	v _{cc} †	MIN	TYP‡	MAX	UNIT	
		I _{OH} = -100 μA		MIN to MAX	V _{CC} -0	.2			
		$I_{OH} = -4 \text{ mA},$	V _{IH} = 2 V	2.7 V	2.2				
Vон		$I_{OH} = -8 \text{ mA},$	V _{IH} = 2 V	2.7 V	2			V	
[$I_{OH} = -6 \text{ mA},$	V _{IH} = 2 V	3 V	2.4				
		$I_{OH} = -12 \text{ mA},$	V _{IH} = 2 V	3 V	2				
		I _{OH} = -100 μA		MIN to MAX			0.2		
		$I_{OH} = -4 \text{ mA},$	V _{IL} = 0.8 V	2.7 V			0.4	V	
VOL		$I_{OH} = -8 \text{ mA},$	V _{IL} = 0.8 V	2.7 V			0.6		
		$I_{OH} = -6 \text{ mA},$	V _{IL} = 0.8 V	3 V			0.55		
		$I_{OH} = -12 \text{ mA},$	V _{IL} = 0.8 V	3 V			0.8		
II		$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ	
l _(hold)		V _I = 0.8 V		3 V	75			μΑ	
		V _I = 2 V] 3 v	-75				
		V _I = 0 to 3.6 V		3.6 V			±500	μΑ	
loz§		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ	
Icc		V _I = V _{CC} or GND,	IO = 0	3.6 V			20	μΑ	
Δlcc		One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	2.7 V to 3.6 V			500	μΑ	
Ci	Control inputs	$V_I = V_{CC}$ or GND		3.3 V		2.5		pF	
C _{io}	A or B ports	$V_O = V_{CC}$ or GND	<u> </u>	3.3 V		3.5		pF	

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} =	3.3 V 3 V	VCC =	2.7 V	UNIT
	(INFOT)	(0011-01)	MIN	MAX	MIN	MAX	
^t pd	A or B	B or A	1.5	7.5	1.5	8.5	ns
^t en	ŌĒ	A or B	1.5	9	1.5	10	ns
^t dis	ŌĒ	A or B	1.5	7.5	1.5	8.5	ns

operating characteristics, $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$

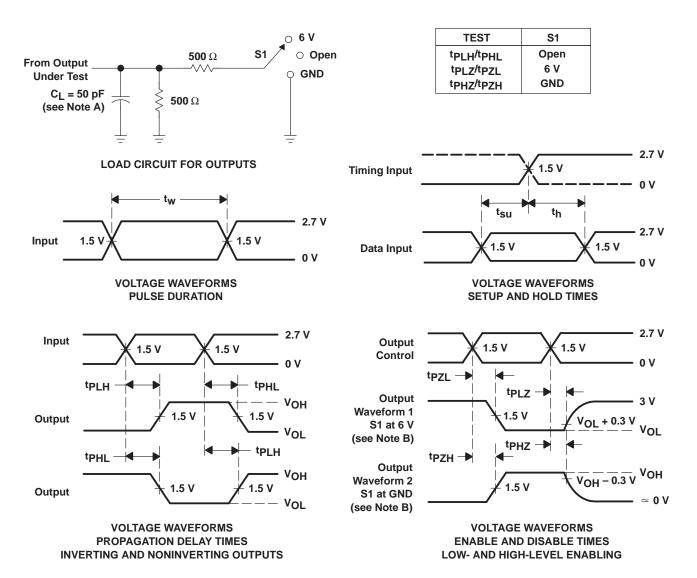
PARAMETER			TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per transceiver	Outputs enabled	Cı = 50 pF. f = 10 MHz	20	pF
		Outputs enabled	$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	2	



 $[\]ddagger$ All typical values are at VCC = 3.3 V, TA = 25°C. \$ For I/O ports, the parameter IOZ includes the input leakage current.

SCES047 - AUGUST 1995

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq 2.5~ns$, $t_f \leq 2.5~ns$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as tden.
- G. tpHL and tpLH are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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